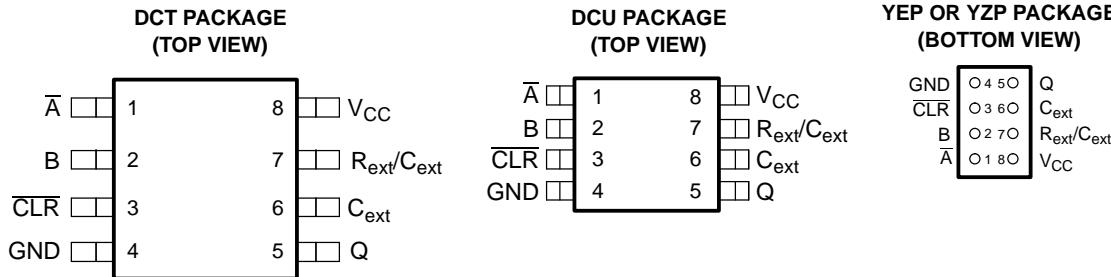


## FEATURES

- Available in the Texas Instruments NanoStar™ and NanoFree™ Packages
- Supports 5-V  $V_{CC}$  Operation
- Inputs Accept Voltages to 5.5 V
- Max  $t_{pd}$  of 8 ns at 3.3 V
- Supports Mixed-Mode Voltage Operation on All Ports
- Schmitt-Trigger Circuitry on  $\bar{A}$  and B Inputs for Slow Input Transition Rates
- Edge Triggered From Active-High or Active-Low Gated Logic Inputs

- Retriggerable for Very Long Output Pulses, up to 100% Duty Cycle
- Overriding Clear Terminates Output Pulse
- Glitch-Free Power-Up Reset on Outputs
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

## DESCRIPTION/ORDERING INFORMATION

The SN74LVC1G123 is a single retriggerable monostable multivibrator designed for 1.65-V to 5.5-V  $V_{CC}$  operation.

This monostable multivibrator features output pulse-duration control by three methods. In the first method, the  $\bar{A}$  input is low, and the B input goes high. In the second method, the B input is high, and the  $\bar{A}$  input goes low. In the third method, the  $\bar{A}$  input is low, the B input is high, and the clear (CLR) input goes high.

### ORDERING INFORMATION

$T_A$	PACKAGE <sup>(1)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING <sup>(2)</sup>
−40°C to 85°C	NanoStar™ – W CSP (DSBGA) 0.23-mm Large Bump – YEP	Reel of 3000	SN74LVC1G123YEPR — D8—
	NanoFree™ – W CSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)		
	SSOP – DCT	Reel of 3000	SN74LVC1G123DCTR C23—
		Reel of 250	
	VSSOP – DCU	Reel of 3000 Reel of 250	SN74LVC1G123DCUR SN74LVC1G123DCUT C23—

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

(2) DCT: The actual top-side marking has three additional characters that designate the year, month, and assembly/test site.  
 DCU: The actual top-side marking has one additional character that designates the assembly/test site.

YEP/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoStar, NanoFree are trademarks of Texas Instruments.

## DESCRIPTION/ORDERING INFORMATION (CONTINUED)

The output pulse duration is programmed by selecting external resistance and capacitance values. The external timing capacitor must be connected between  $C_{ext}$  and  $R_{ext}/C_{ext}$  (positive) and an external resistor connected between  $R_{ext}/C_{ext}$  and  $V_{CC}$ . To obtain variable pulse durations, connect an external variable resistance between  $R_{ext}/C_{ext}$  and  $V_{CC}$ . The output pulse duration also can be reduced by taking CLR low.

Pulse triggering occurs at a particular voltage level and is not directly related to the transition time of the input pulse. The  $\bar{A}$  and B inputs have Schmitt triggers with sufficient hysteresis to handle slow input transition rates with jitter-free triggering at the outputs.

Once triggered, the basic pulse duration can be extended by retriggering the gated low-level-active ( $\bar{A}$ ) or high-level-active (B) input. Pulse duration can be reduced by taking CLR low. CLR can be used to override  $\bar{A}$  or B inputs. The input/output timing diagram illustrates pulse control by retriggering the inputs and early clearing.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

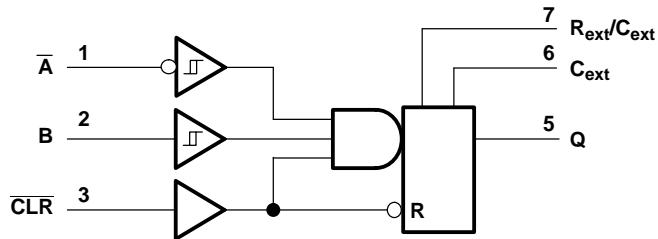
NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

FUNCTION TABLE

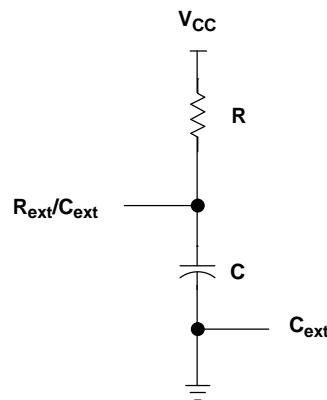
INPUTS			OUTPUTS
CLR	$\bar{A}$	B	Q
L	X	X	L
X	H	X	$L^{(1)}$
X	X	L	$L^{(1)}$
H	L	$\uparrow$	$\square$
H	$\downarrow$	H	$\square$
$\uparrow$	L	H	$\square$

(1) These outputs are based on the assumption that the indicated steady-state conditions at the A and B inputs have been set up long enough to complete any pulse started before the setup.

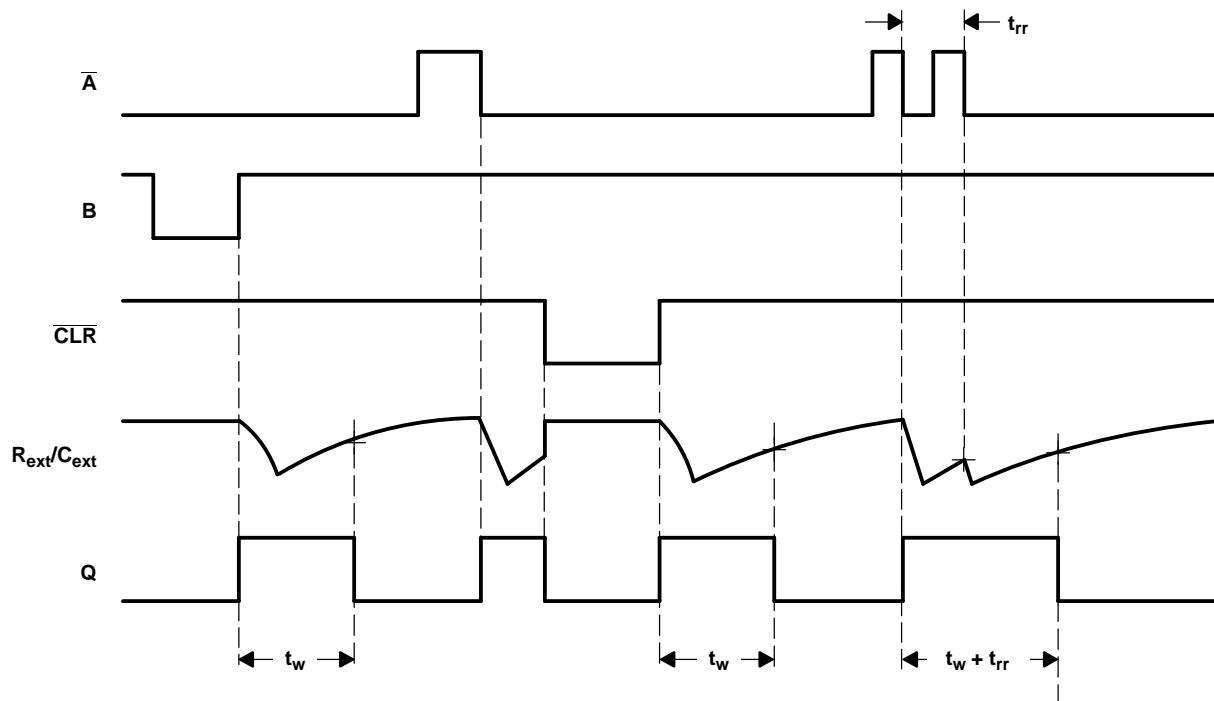
LOGIC DIAGRAM (POSITIVE LOGIC)



REQUIRED TIMING CIRCUIT



INPUT/OUTPUT TIMING DIAGRAM



**SN74LVC1G123**  
**SINGLE RETRIGGERABLE MONOSTABLE MULTIVIBRATOR**  
**WITH SCHMITT-TRIGGER INPUTS**

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**Absolute Maximum Ratings<sup>(1)</sup>**

over operating free-air temperature range (unless otherwise noted)

		<b>MIN</b>	<b>MAX</b>	<b>UNIT</b>
$V_{CC}$	Supply voltage range	-0.5	6.5	V
$V_I$	Input voltage range <sup>(2)</sup>	-0.5	6.5	V
$V_O$	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	-0.5	6.5	V
$V_O$	Voltage range applied to any output in the high or low state <sup>(2)(3)</sup>	-0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current $V_I < 0$		-50	mA
$I_{OK}$	Output clamp current $V_O < 0$		-50	mA
$I_O$	Continuous output current		$\pm 50$	mA
	Continuous current through $V_{CC}$ or GND		$\pm 100$	mA
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	DCT package	220	°C/W
		DCU package	227	
		YEP/YZP package	102	
$T_{stg}$	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- (3) The value of  $V_{CC}$  is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

**Recommended Operating Conditions<sup>(1)</sup>**

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	Operating	1.65	5.5	V
		Data retention only	1.5		
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>		V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		
		V <sub>CC</sub> = 3 V to 3.6 V	2		
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.7 × V <sub>CC</sub>		
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.35 × V <sub>CC</sub>		V
		V <sub>CC</sub> = 2.3 V to 2.7 V	0.7		
		V <sub>CC</sub> = 3 V to 3.6 V	0.8		
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.3 × V <sub>CC</sub>		
V <sub>I</sub>	Input voltage		0	5.5	V
V <sub>O</sub>	Output voltage		0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 1.65 V		-4	mA
		V <sub>CC</sub> = 2.3 V		-8	
		V <sub>CC</sub> = 3 V		-16	
		V <sub>CC</sub> = 4.5 V		-24	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 1.65 V		4	mA
		V <sub>CC</sub> = 2.3 V		8	
		V <sub>CC</sub> = 3 V		16	
		V <sub>CC</sub> = 4.5 V		24	
R <sub>ext</sub> <sup>(2)</sup>	External timing resistance	V <sub>CC</sub> = 2 V		5 k	Ω
		V <sub>CC</sub> ≥ 3 V		1 k	
T <sub>A</sub>	Operating free-air temperature		-40	85	°C

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

(2) R<sub>ext</sub>/C<sub>ext</sub> is an I/O and must not be connected directly to GND or V<sub>CC</sub>.

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**Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>OH</sub>	I <sub>OH</sub> = -100 $\mu$ A		1.65 V to 5.5 V	V <sub>CC</sub> - 0.1			V
	I <sub>OH</sub> = -4 mA		1.65 V	1.2			
	I <sub>OH</sub> = -8 mA		2.3 V	1.9			
	I <sub>OH</sub> = -16 mA		3 V	2.4			
	I <sub>OH</sub> = -24 mA			2.3			
	I <sub>OH</sub> = -32 mA		4.5 V	3.8			
V <sub>OL</sub>	I <sub>OL</sub> = 100 $\mu$ A		1.65 V to 5.5 V		0.1		V
	I <sub>OL</sub> = 4 mA		1.65 V		0.45		
	I <sub>OL</sub> = 8 mA		2.3 V		0.3		
	I <sub>OL</sub> = 16 mA		3 V		0.4		
	I <sub>OL</sub> = 24 mA				0.55		
	I <sub>OL</sub> = 32 mA		4.5 V		0.55		
I <sub>I</sub>	R <sub>ext</sub> /C <sub>ext</sub> <sup>(2)</sup>	B = GND, $\bar{A} = \bar{CLR} = V_{CC}$	1.65 V to 5.5 V		$\pm 0.25$		$\mu$ A
	$\bar{A}$ , B, $\bar{CLR}$	V <sub>I</sub> = 5.5 V or GND			$\pm 1$		
I <sub>off</sub>	$\bar{A}$ , B, Q, $\bar{CLR}$	V <sub>I</sub> or V <sub>O</sub> = 5.5 V		0		$\pm 10$	$\mu$ A
I <sub>CC</sub>	Quiescent	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0		5.5 V		20	$\mu$ A
I <sub>CC</sub>	Active state	V <sub>I</sub> = V <sub>CC</sub> or GND, R <sub>ext</sub> /C <sub>ext</sub> = 0.5 V <sub>CC</sub>	1.65 V		165		$\mu$ A
			2.3 V		220		
			3 V		280		
			4.5 V		650		
			5.5 V		975		
C <sub>i</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V		3		pF

(1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

(2) This test is performed with the terminal in the off-state condition.

**Timing Requirements**

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V ± 0.15 V	V <sub>CC</sub> = 2.5 V ± 0.2 V	V <sub>CC</sub> = 3.3 V ± 0.3 V	V <sub>CC</sub> = 5 V ± 0.5 V	UNIT	
			MIN	TYP	MIN	TYP		
t <sub>wIN</sub>	Pulse duration	$\bar{CLR}$ $\bar{A}$ or B trigger	8	4	3	2.5	ns	
			8	4	3	2.5		
t <sub>rr</sub>	Pulse retrigger time	$\bar{CLR}$	R <sub>ext</sub> = 1 k $\Omega$ C <sub>ext</sub> = 100 pF			5.5	4.5	ns
			C <sub>ext</sub> = 100 $\mu$ F			1.4	1.1	$\mu$ s
		Q	R <sub>ext</sub> = 5 k $\Omega$ C <sub>ext</sub> = 100 pF	75	45			ns
			C <sub>ext</sub> = 100 $\mu$ F	1.8	1.4			$\mu$ s

**Switching Characteristics**

over recommended operating free-air temperature range, C<sub>L</sub> = 15 pF (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 1.8 V ± 0.15 V			V <sub>CC</sub> = 2.5 V ± 0.2 V			V <sub>CC</sub> = 3.3 V ± 0.3 V			V <sub>CC</sub> = 5 V ± 0.5 V			UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
t <sub>pd</sub>	$\bar{A}$ or B	Q	7	18.5	52	4	17	3	11.5	2	7.6	ns			
			5	12.4	34	3	11.5	2	8	1.5	5.5				
			7	17.4	54	4	15.5	3	10.5	2	7				

## Switching Characteristics

over recommended operating free-air temperature range,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see [Figure 2](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$			$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$			$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$			$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$			UNIT
				MIN	TYP <sup>(1)</sup>	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
$t_{pd}$	$\overline{A}$ or B	Q		6	18.6	57	3	18.5	2	12.5	1.5	8.2	ns			
	$\overline{CLR}$			4	11.6	36.5	2	12.5	1.5	8.6	1.5	6				
	$\overline{CLR}$ trigger			5	17.3	59	2.5	17	2	11.5	1.5	7.5				
$t_w$ OUT <sup>(2)</sup>		Q	$C_{ext} = 28 \text{ pF}$ , $R_{ext} = 2 \text{ k}\Omega$	225	600	190	220	170	200	150	180	ns				
			$C_{ext} = 0.01 \mu\text{F}$ , $R_{ext} = 10 \text{ k}\Omega$	100	110	100	110	100	110	100	110					
			$C_{ext} = 0.1 \mu\text{F}$ , $R_{ext} = 10 \text{ k}\Omega$	1	1.1	1	1.1	1	1.1	1	1.1					

(1)  $T_A = 25^\circ\text{C}$

(2)  $t_w$  = Duration of pulse at Q output

## Operating Characteristics

$T_A = 25^\circ\text{C}$

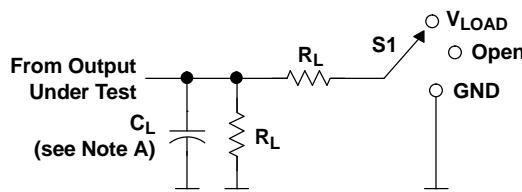
PARAMETER	TEST CONDITIONS	$V_{CC} = 1.8 \text{ V}$	$V_{CC} = 2.5 \text{ V}$	$V_{CC} = 3.3 \text{ V}$	$V_{CC} = 5 \text{ V}$	UNIT	
		TYP	TYP	TYP	TYP		
Cpd	Power dissipation capacitance $\overline{A}$ = low, B = high, $CLR = 10 \text{ MHz}$	$R_{ext} = 1 \text{ k}\Omega$ , No $C_{ext}$			35	37	pF
		$R_{ext} = 5 \text{ k}\Omega$ , No $C_{ext}$	41	40			

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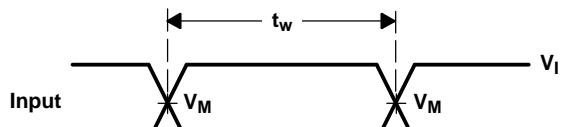
**PARAMETER MEASUREMENT INFORMATION**



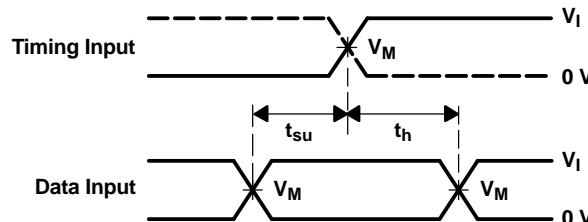
TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

**LOAD CIRCUIT**

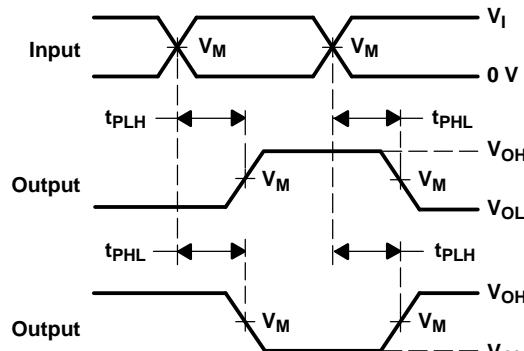
$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_\Delta$
	$V_I$	$t_r/t_f$					
$1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC}$	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	1 M $\Omega$	0.15 V
$2.5 \text{ V} \pm 0.2 \text{ V}$	$V_{CC}$	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	1 M $\Omega$	0.15 V
$3.3 \text{ V} \pm 0.3 \text{ V}$	3 V	$\leq 2.5 \text{ ns}$	1.5 V	6 V	15 pF	1 M $\Omega$	0.3 V
$5 \text{ V} \pm 0.5 \text{ V}$	$V_{CC}$	$\leq 2.5 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	1 M $\Omega$	0.3 V



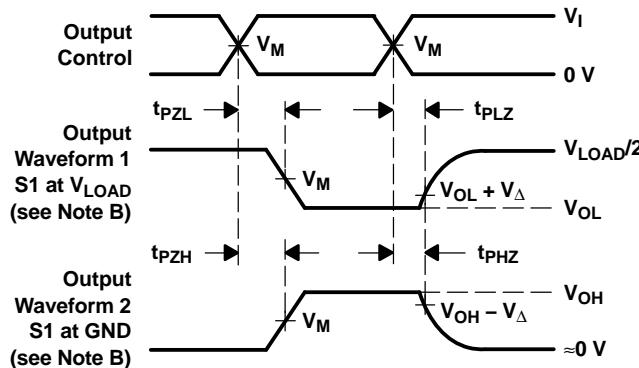
**VOLTAGE WAVEFORMS  
PULSE DURATION**



**VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS**



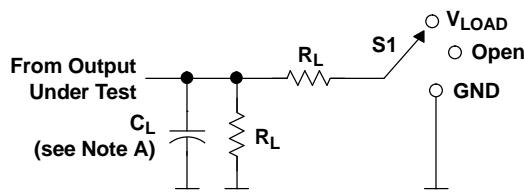
**VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING**

NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

**Figure 1. Load Circuit and Voltage Waveforms**

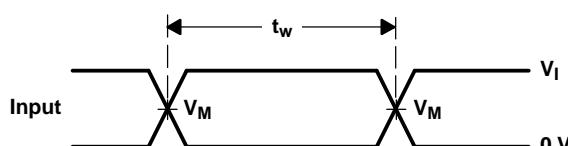
PARAMETER MEASUREMENT INFORMATION



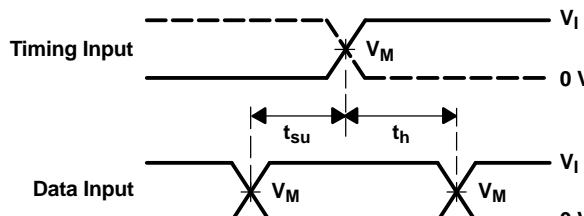
TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

LOAD CIRCUIT

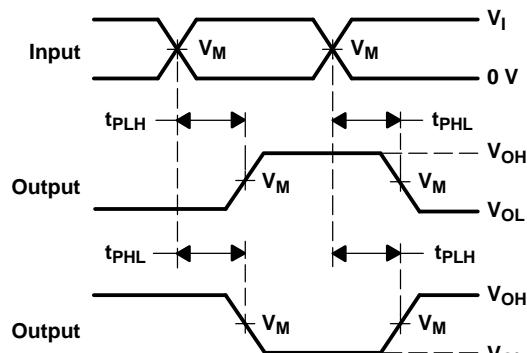
$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_\Delta$
	$V_I$	$t_r/t_f$					
$1.8 \text{ V} \pm 0.15 \text{ V}$	$V_{CC}$	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5 \text{ V} \pm 0.2 \text{ V}$	$V_{CC}$	$\leq 2 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
$3.3 \text{ V} \pm 0.3 \text{ V}$	3 V	$\leq 2.5 \text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$5 \text{ V} \pm 0.5 \text{ V}$	$V_{CC}$	$\leq 2.5 \text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	50 pF	500 $\Omega$	0.3 V



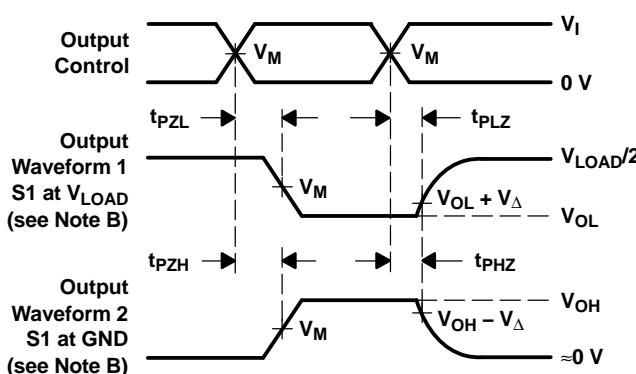
VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING

NOTES: A.  $C_L$  includes probe and jig capacitance.

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- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{dis}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms

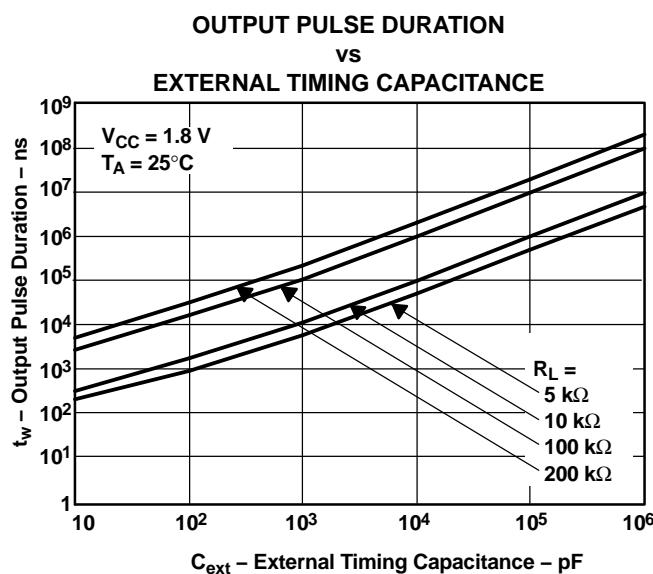
APPLICATION INFORMATION<sup>(1)</sup>

Figure 3.

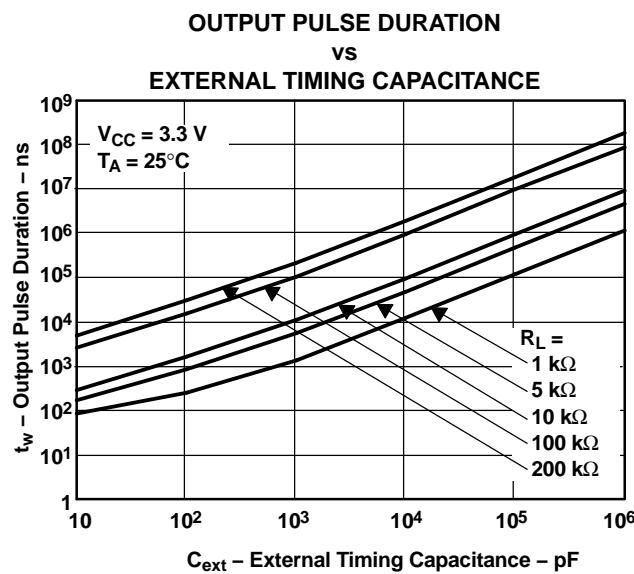


Figure 4.

(1) Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

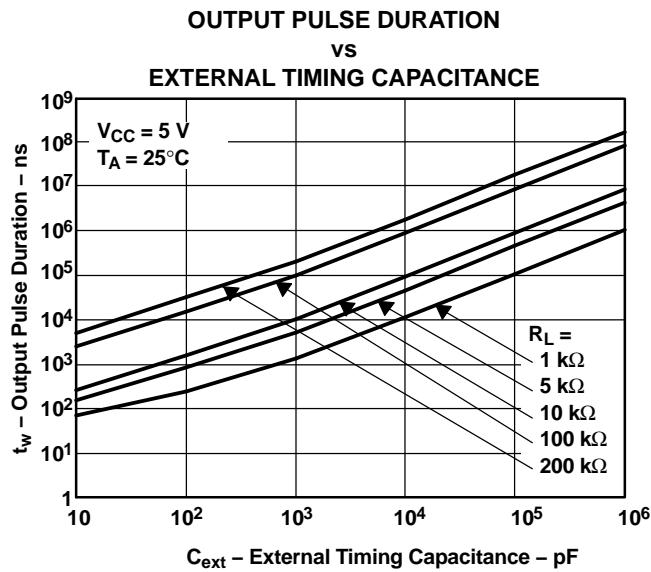


Figure 5.

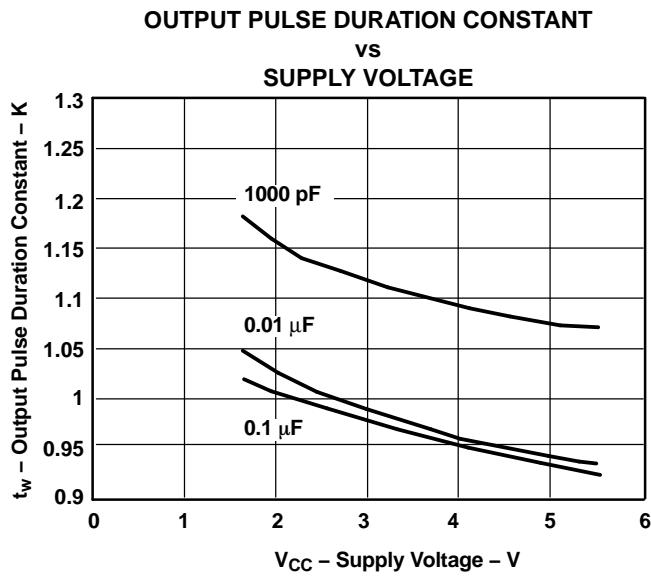


Figure 6.

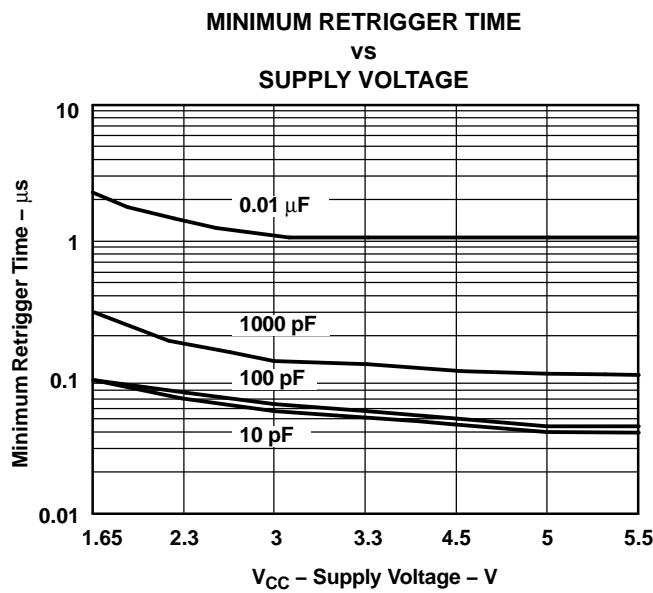


Figure 7.

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74LVC1G123DCTRE4	ACTIVE	SM8	DCT	8	3000	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM
74LVC1G123DCTTE4	ACTIVE	SM8	DCT	8	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM
74LVC1G123DCURE4	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74LVC1G123DCUTE4	ACTIVE	US8	DCU	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G123DCTR	ACTIVE	SM8	DCT	8	3000	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G123DCTT	ACTIVE	SM8	DCT	8	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G123DCUR	ACTIVE	US8	DCU	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G123DCUT	ACTIVE	US8	DCU	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G123YEPR	NRND	WCSP	YEP	8	3000	TBD	SNPB	Level-1-260C-UNLIM
SN74LVC1G123YZPR	ACTIVE	WCSP	YZP	8	3000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

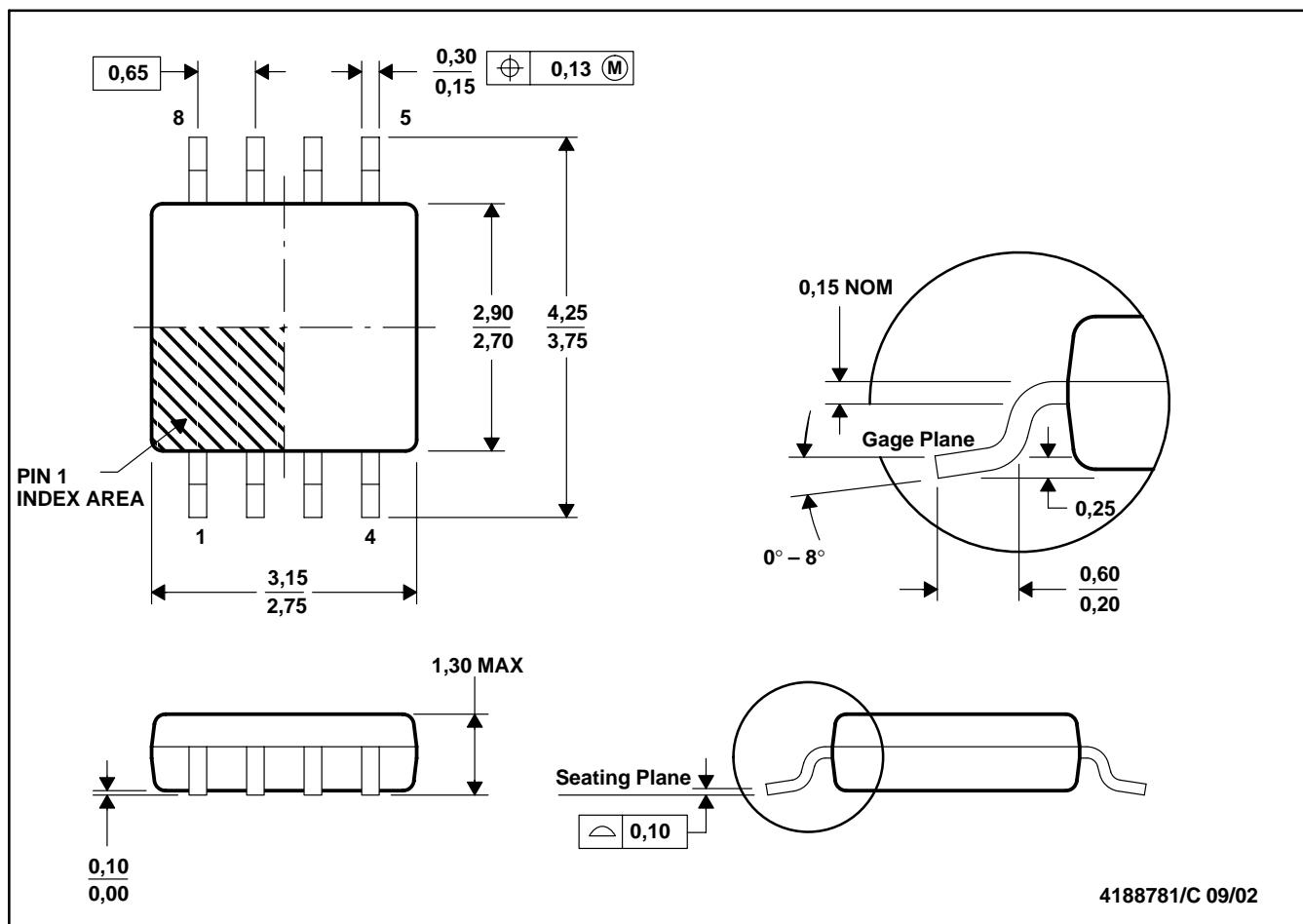
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## DCT (R-PDSO-G8)

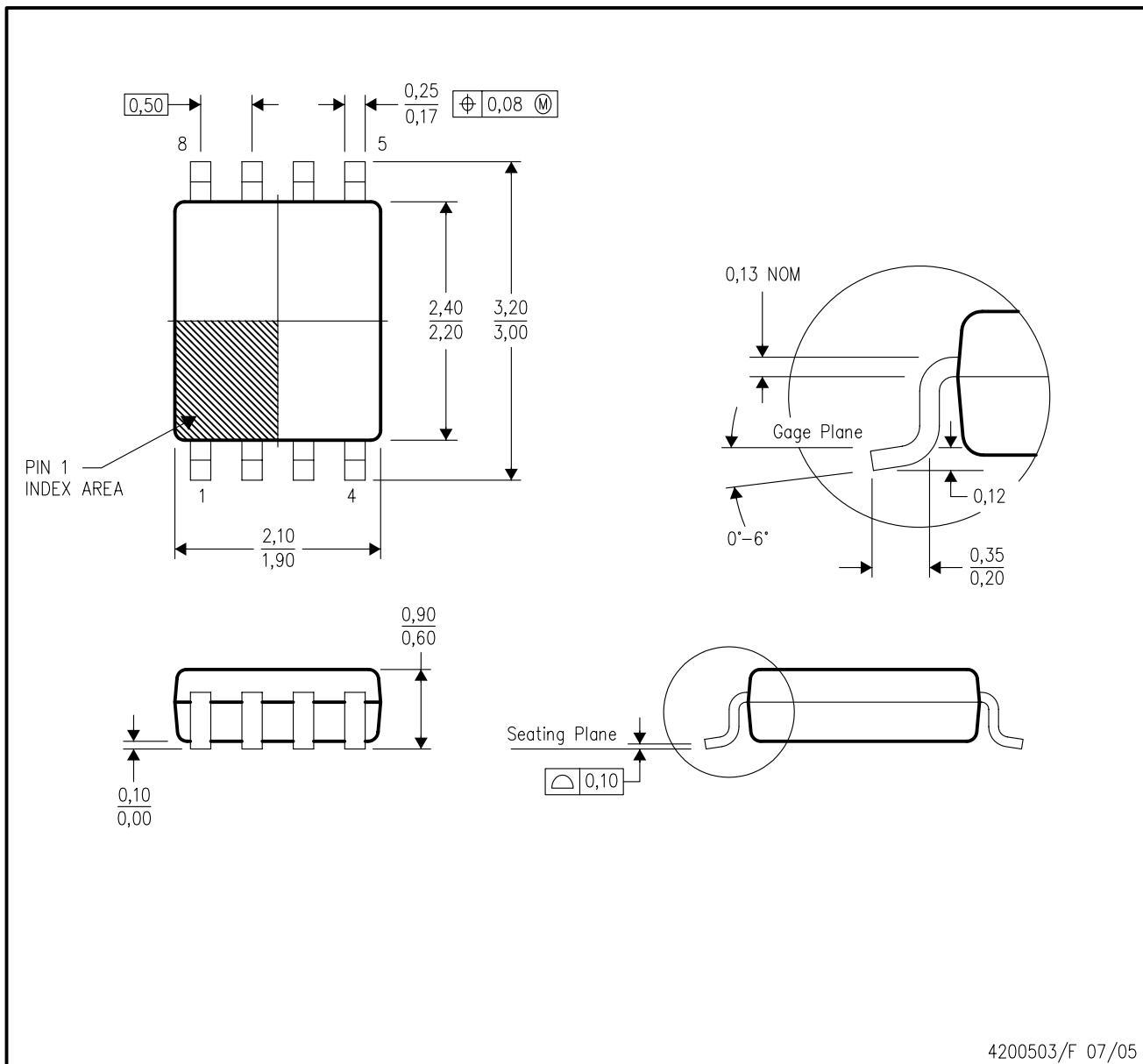
## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion  
 D. Falls within JEDEC MO-187 variation DA.

## DCU (R-PDSO-G8)

## PLASTIC SMALL-OUTLINE PACKAGE (DIE DOWN)



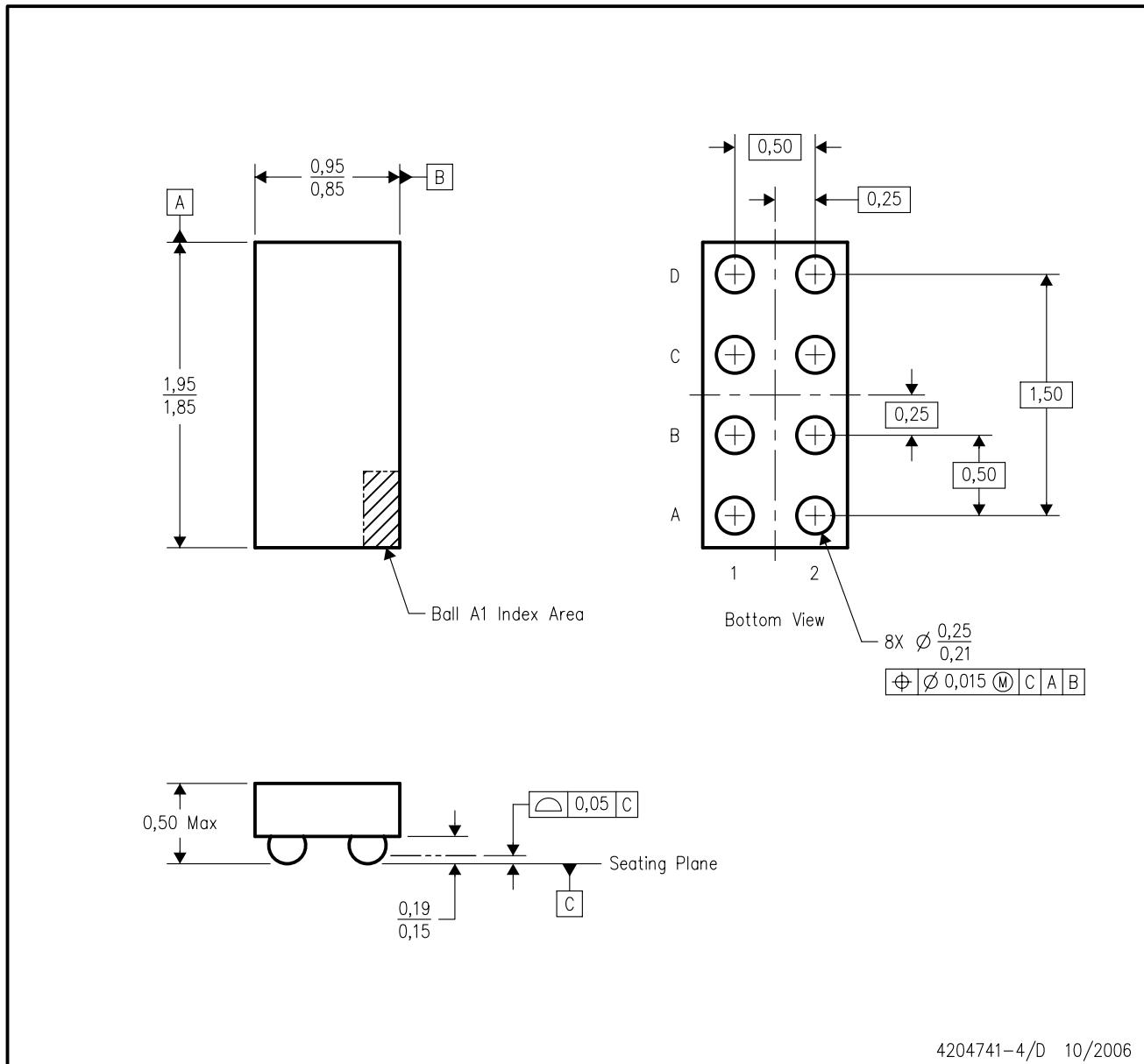
4200503/F 07/05

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- Falls within JEDEC MO-187 variation CA.

## YZP (R-XBGA-N8)

## DIE-SIZE BALL GRID ARRAY



4204741-4/D 10/2006

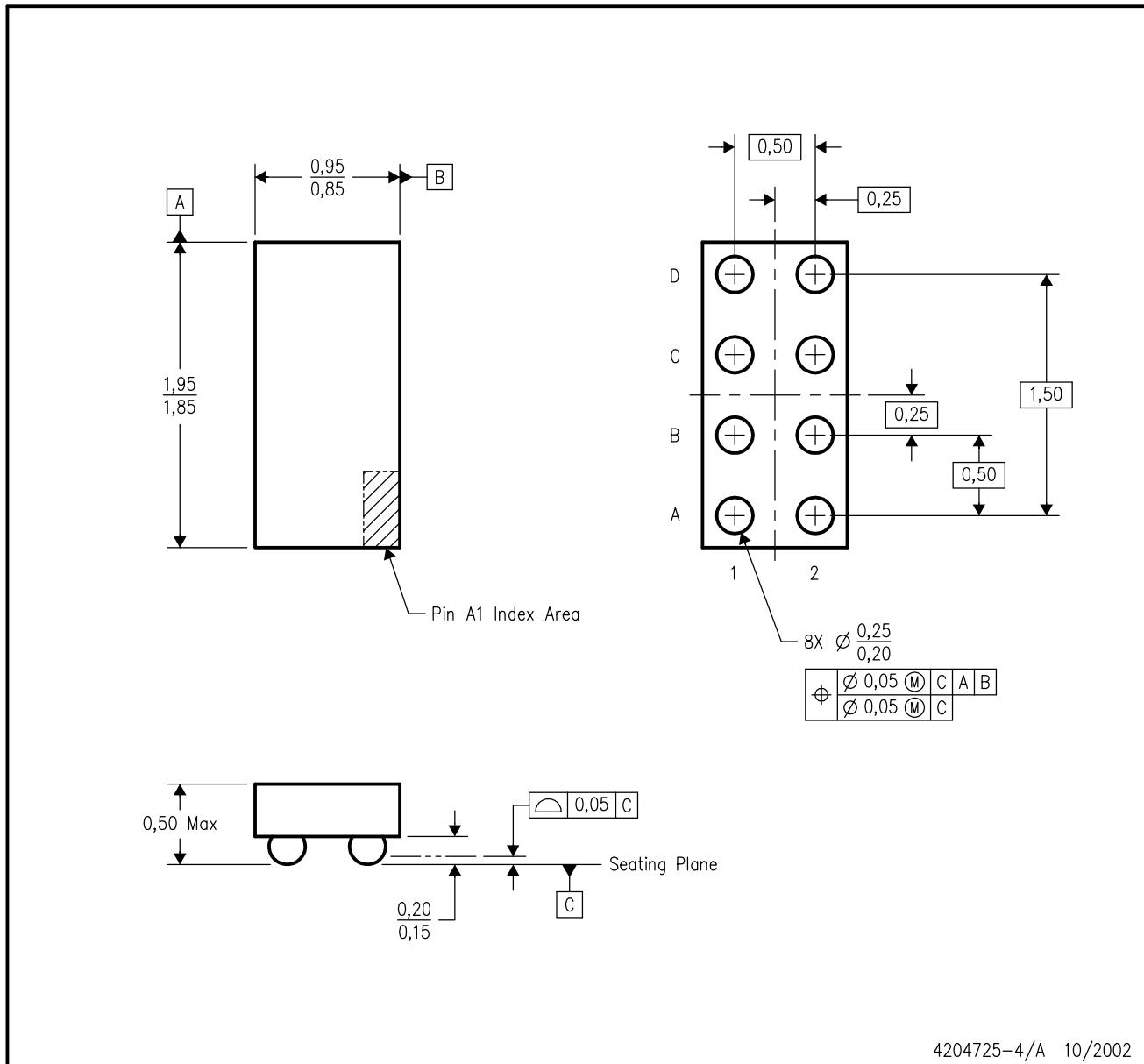
NOTES:

- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- NanoFree™ package configuration.
- This package is lead-free. Refer to the 8 YEP package (drawing 4204725) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.

## YEP (R-XBGA-N8)

## DIE-SIZE BALL GRID ARRAY



NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- NanoStar™ package configuration.
- This package is tin-lead (SnPb). Refer to the 8 YZP package (drawing 4204741) for lead-free.

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